

RELIABILITY MONITOR

PRODUCT	MONITOR DATE	DATE CODE	ASSEMBLY FACILITY	ASSEMBLY LOT NO	PROCESS TYPE	PACKAGE TYPE
DS1620	Mar-97	9706 C2	OMEDATA	DD641641AAB	1.2μ OX/NI	08 SOIC 208

STRESS/JOB NO.

**READPOINT
(Sample Size/No. of Fails)**

Preconditioning (P/C):
HTC Vapor Phase
P-19420

<u>Electrical</u>	<u>Cum %</u>
235/0	0.0%

Sonoscan
P-19605

<u>Post Vapor Phase</u>
4/1
F1

Infant / High Voltage Life
125°C, 7.0 V.
P-19606, P-19634

<u>48 Hr</u>	<u>336 Hr</u>	<u>1KHr</u>	<u>*Failure Rate</u>
231/0	77/0	77/0	30 Fits

*Chi Squared Method, 60% C. L., 55°C & 5.5V; Temperature Derating: Ea = 0.7 ev; Voltage Derating B = 1.0

Temp Cycle
-55°C to +125°C
P-19635

<u>300 ~</u>	<u>1K ~</u>	<u>Cum %</u>
39/0	39/0	0.0%

Biased Moisture (HAST)
120°C/85% RH, 5.5 V.
P-19636

<u>100 Hr</u>	<u>Cum %</u>
66/0	0.0%

Failure Mode

F1: Delamination

Failure Analysis

No failures after Reliability stresses.